

PS7342-1A, PS7342L-1A

6-PIN DIP, HIGH ISOLATION VOLTAGE 1-ch Optical Coupled MOS FET

DESCRIPTION

The PS7342-1A and PS7342L-1A are solid state relays containing GaAs LEDs on the light emitting side (input side) and MOS FETs on the output side.

They are suitable for analog signal control because of their low offset and high linearity.

The PS7342L-1A has a surface mount type lead.

★ FEATURES

- High isolation voltage ($BV = 3\,750\text{ V.r.m.s.}$)
- 1 channel type (1 a output)
- Low LED Operating Current ($I_F = 2\text{ mA}$)
- Designed for AC/DC switching line changer
- Small package (6-pin DIP)
- Low offset voltage
- PS7342L-1A: Surface mount type
- UL approved: File No. E72422 (S)
- BSI approved: No. 8252/8253
- CSA approved: No. CA 101391

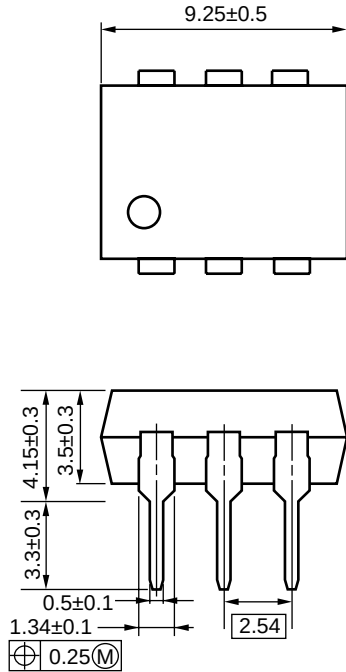
APPLICATIONS

- Exchange equipment
- Measurement equipment
- FA/OA equipment

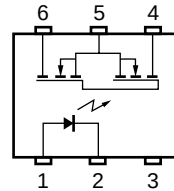
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Not all devices/types available in every country. Please check with local NEC representative for availability and additional information.

PACKAGE DIMENSIONS (in millimeters)

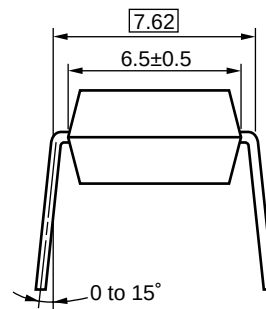
PS7342-1A



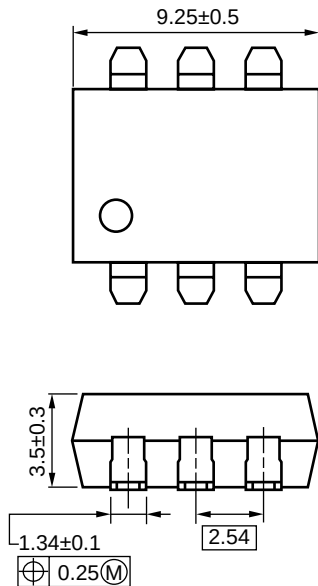
TOP VIEW



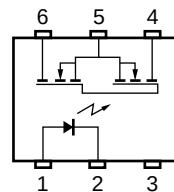
1. LED Anode
2. LED Cathode
3. NC
4. MOS FET Drain
5. MOS FET Source
6. MOS FET Drain



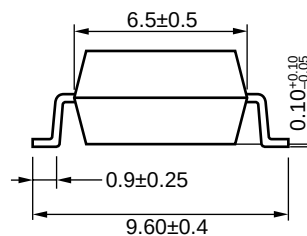
PS7342L-1A



TOP VIEW



1. LED Anode
2. LED Cathode
3. NC
4. MOS FET Drain
5. MOS FET Source
6. MOS FET Drain



★ ORDERING INFORMATION

Part Number	Package	Packing Style	Application Part Number ^{*1}
PS7342-1A	6-pin DIP	Magazine case 50 pcs	PS7342-1A
PS7342L-1A			PS7342L-1A
PS7342L-1A-E3		Embossed Tape 1 000 pcs/reel	
PS7342L-1A-E4			

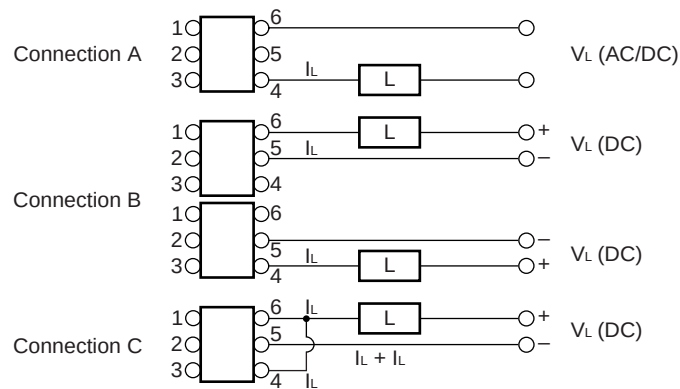
^{*1} For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

Parameter			Symbol	Ratings	Unit
Diode	Forward Current (DC)		I _F	50	mA
	Reverse Voltage		V _R	5.0	V
	Power Dissipation		P _D	50	mW
	Peak Forward Current ^{*1}		I _{FP}	1	A
MOS FET	Break Down Voltage		V _L	400	V
	Continuous Load Current ^{*2}	Connection A	I _L	200	mA
		Connection B		250	
		Connection C		400	
	Pulse Load Current ^{*3} (AC/DC Connection)		I _{LP}	400	mA
	Power Dissipation		P _D	560	mW
Isolation Voltage ^{*4}			BV	3 750	Vr.m.s.
Total Power Dissipation			P _T	610	mW
Operating Ambient Temperature			T _A	−40 to +85	°C
Storage Temperature			T _{stg}	−40 to +125	°C

***1** $PW = 100\text{ }\mu\text{s}$, Duty Cycle = 1 %

***2** Conditions: $I_F \geq 2\text{ mA}$. The following types of load connections are available.



***3** $PW = 100\text{ ms}$, 1 shot

***4** AC voltage for 1 minute at $T_A = 25\text{ }^{\circ}\text{C}$, $RH = 60\text{ }\%$ between input and output

RECOMMENDED OPERATING CONDITIONS ($T_A = 25\text{ }^{\circ}\text{C}$)

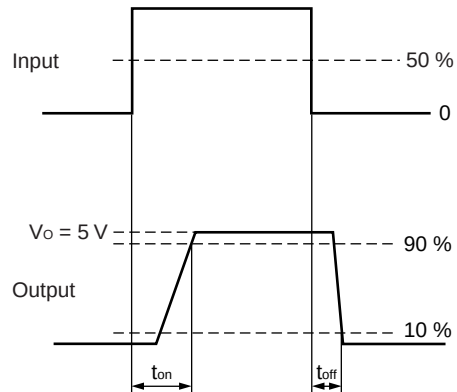
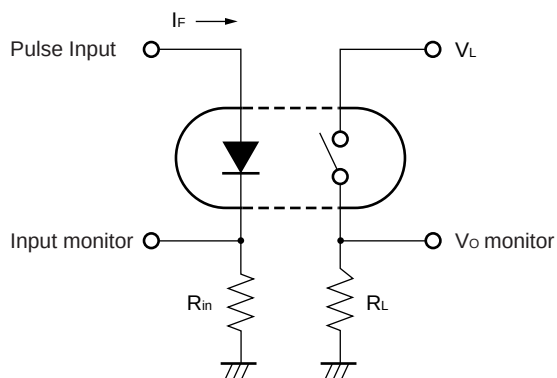
Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	I_F	2	10	20	mA
LED Off Voltage	V_F	0		0.5	V

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★ ELECTRICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$)

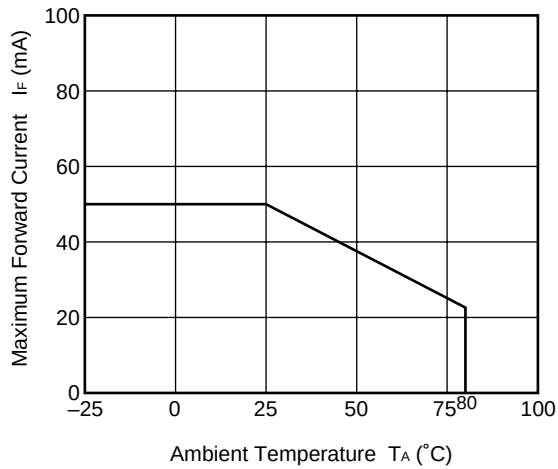
Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V_F	$I_F = 10\text{ mA}$		1.2	1.4	V
	Reverse Current	I_R	$V_R = 5\text{ V}$			5.0	μA
MOS FET	Off-state Leakage Current	I_{Leak}	$V_D = 400\text{ V}$		0.03	1.0	μA
	Output Capacitance	C_{out}	$V_D = 0\text{ V}, f = 1\text{ MHz}$		225		pF
Coupled	LED On-state Current	I_{Fon}	$I_L = 200\text{ mA}$			2.0	mA
	On-state Resistance	R_{on1}	$I_F = 10\text{ mA}, I_L = 10\text{ mA}$		6	10	Ω
		R_{on2}	$I_F = 10\text{ mA}, I_L = 200\text{ mA}, t \leq 10\text{ ms}$				
	Turn-on Time ^{*1}	t_{on}	$I_F = 10\text{ mA}, V_O = 5\text{ V}, PW \geq 10\text{ ms}$		1.2	2.5	ms
	Turn-off Time ^{*1}	t_{off}			0.06	0.2	
	Isolation Resistance	$R_{\text{I-O}}$	$V_{\text{I-O}} = 1.0\text{ kV}_{\text{DC}}$	10^9			Ω
	Isolation Capacitance	$C_{\text{I-O}}$	$V = 0\text{ V}, f = 1\text{ MHz}$		1.1		pF

*1 Test Circuit for Switching Time

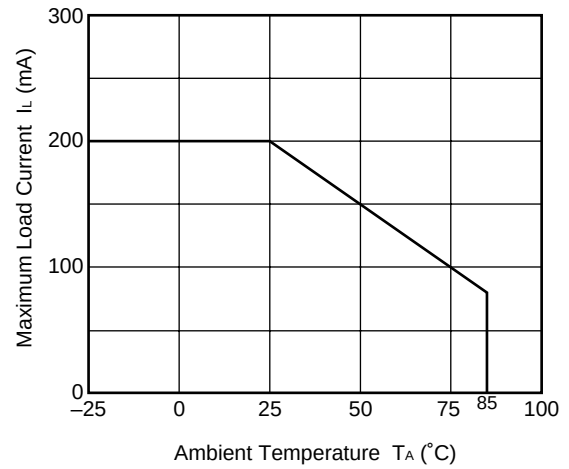


★ TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise specified)

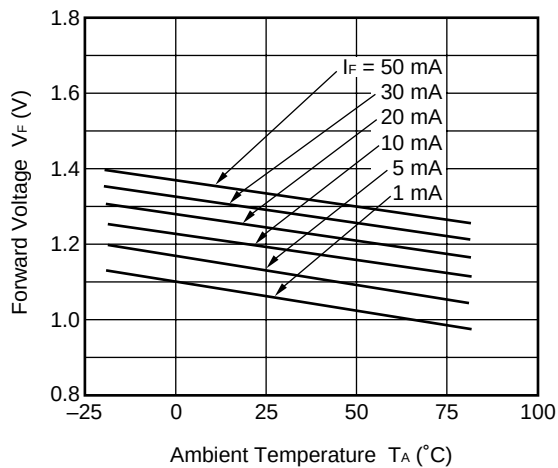
MAXIMUM FORWARD CURRENT vs. AMBIENT TEMPERATURE



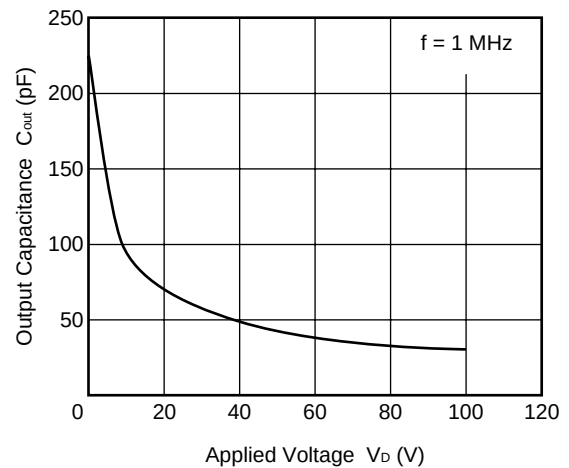
MAXIMUM LOAD CURRENT vs. AMBIENT TEMPERATURE



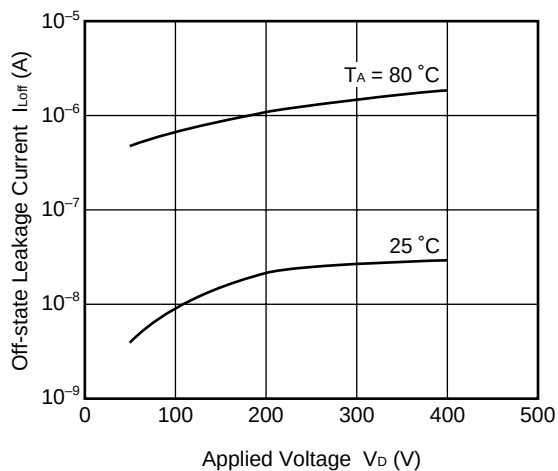
FORWARD VOLTAGE vs. AMBIENT TEMPERATURE



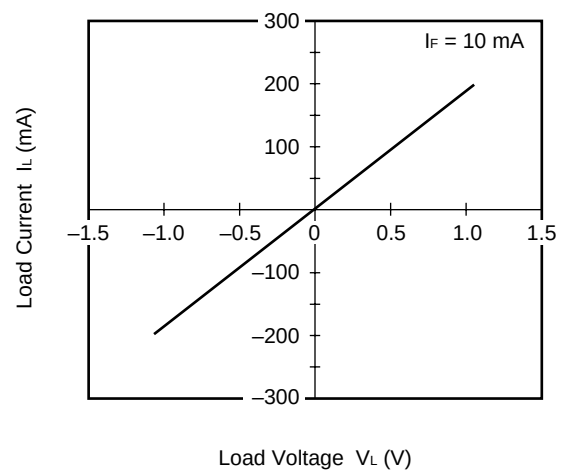
OUTPUT CAPACITANCE vs. APPLIED VOLTAGE



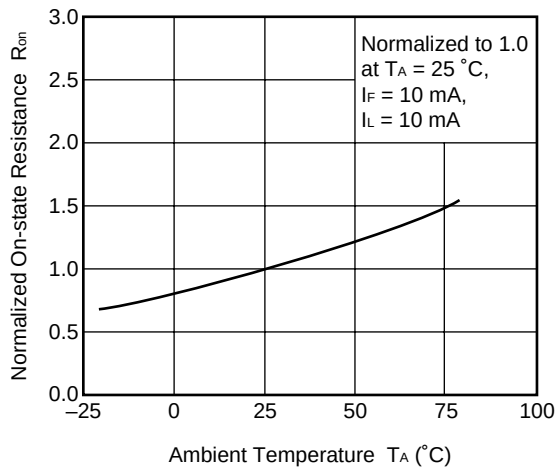
OFF-STATE LEAKAGE CURRENT vs. APPLIED VOLTAGE



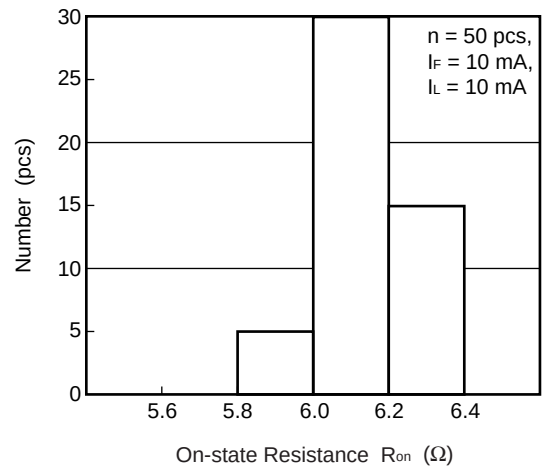
LORD CURRENT vs. LORD VOLTAGE



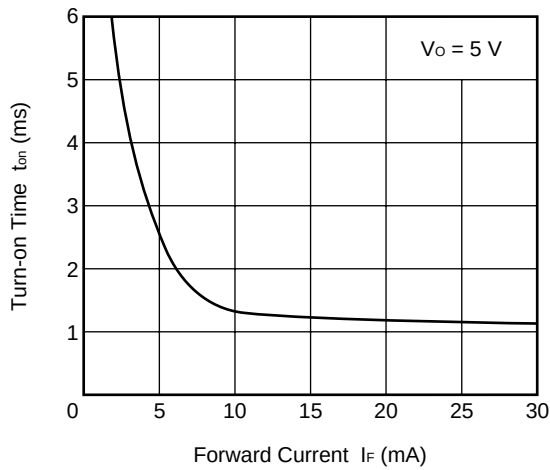
NORMALIZED ON-STATE RESISTANCE vs. AMBIENT TEMPERATURE



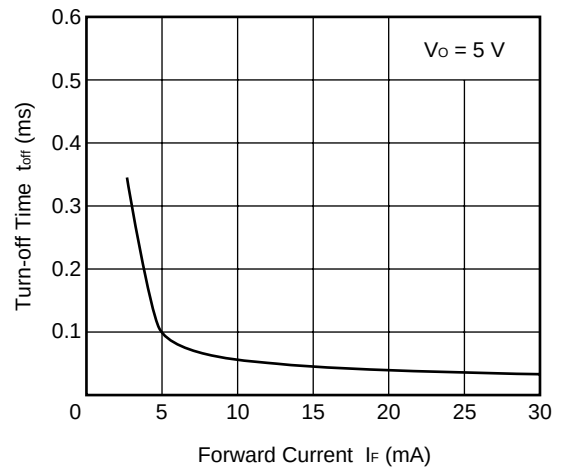
ON-STATE RESISTANCE DISTRIBUTION



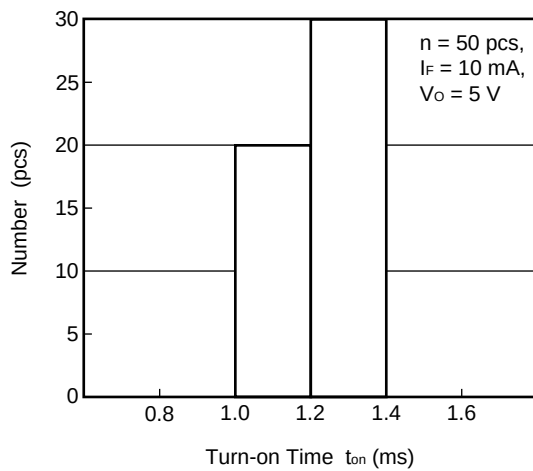
TURN-ON TIME vs. FORWARD CURRENT



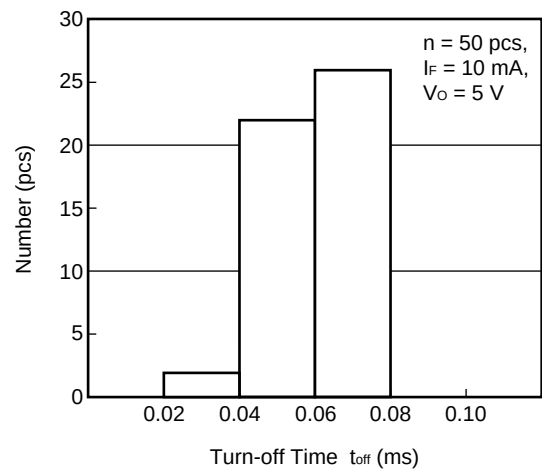
TURN-OFF TIME vs. FORWARD CURRENT

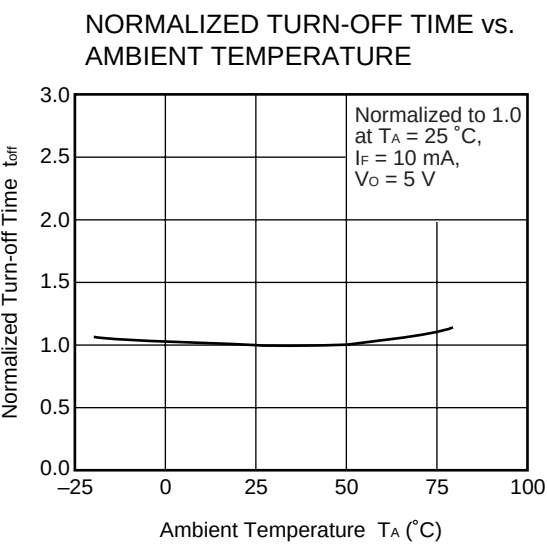
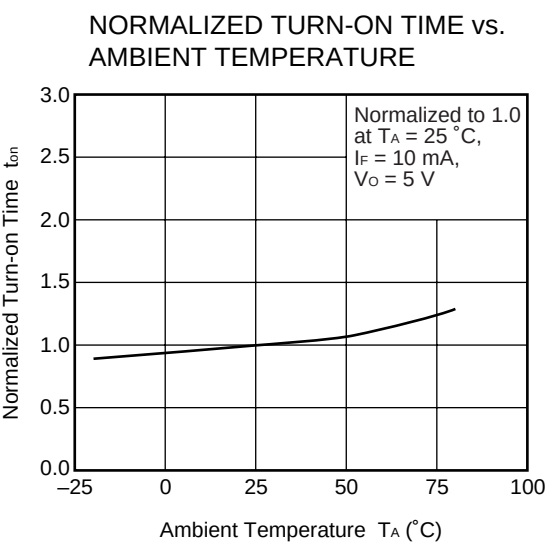


TURN-ON TIME DISTRIBUTION



TURN-OFF TIME DISTRIBUTION

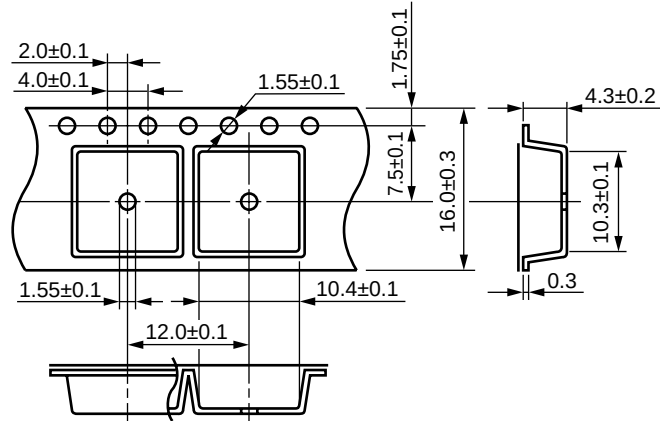




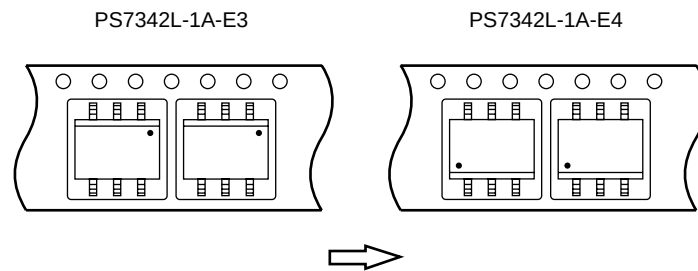
Remark The graphs indicate nominal characteristics.

★ TAPING SPECIFICATIONS (in millimeters)

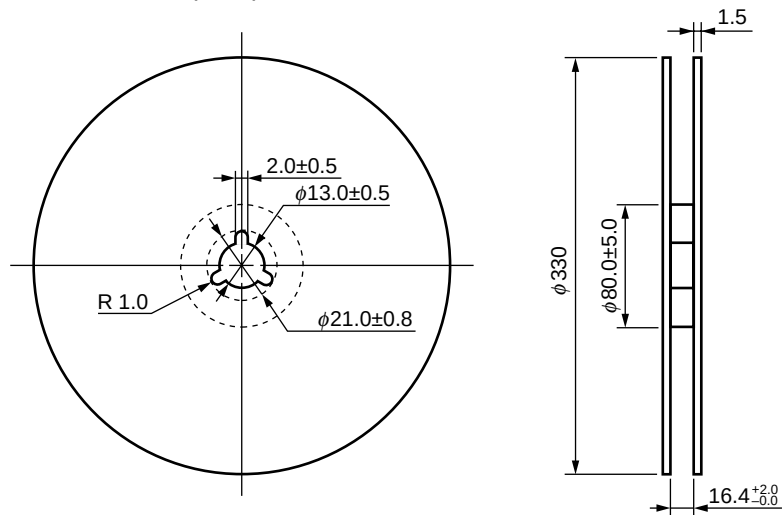
Outline and Dimensions (Tape)



Tape Direction



Outline and Dimensions (Reel)



Packing: 1 000 pcs/reel

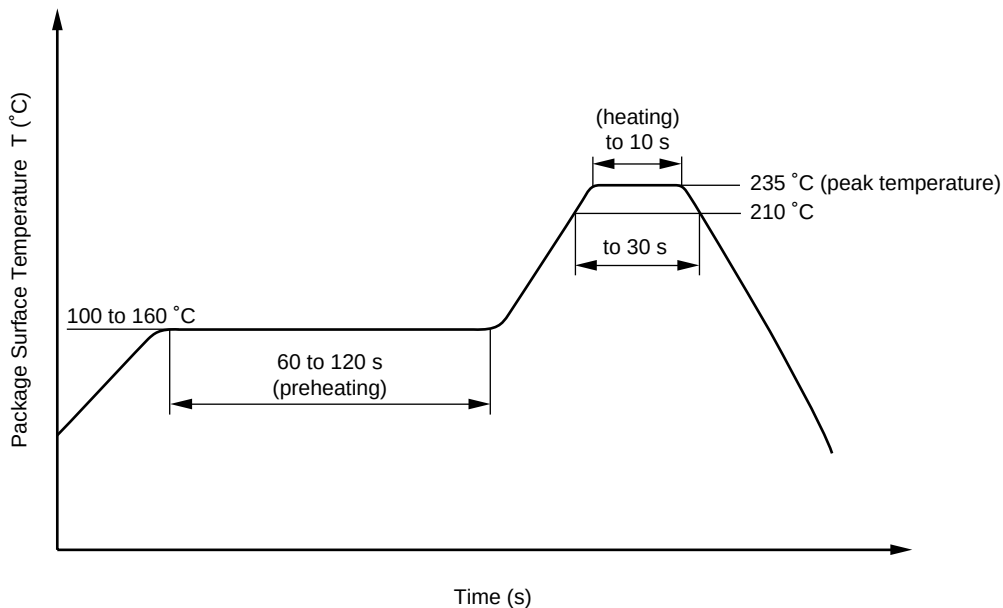
RECOMMENDED SOLDERING CONDITIONS

(1) Infrared reflow soldering

- Peak reflow temperature 235 °C (package surface temperature)
- Time of temperature higher than 210 °C 30 seconds or less
- Number of reflows One
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt % is recommended.)

★

Recommended Temperature Profile of Infrared Reflow



(2) Dip soldering

- Temperature 260 °C or below (molten solder temperature)
- Time 10 seconds or less
- Number of times One
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt % is recommended.)

(3) Cautions

- Fluxes
Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.
- Products in dry pack
After opening the dry pack, solder the products within the valid storage period specified on the label on the dry pack.

[MEMO]

CAUTION

Within this device there exists GaAs (Gallium Arsenide) material which is a harmful substance if ingested. Please do not under any circumstances break the hermetic seal.

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 - Special: Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support)
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